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STPS1545C-Y

Automotive power Schottky rectifier

Features

- Very small conduction losses
- Negligible switching losses
- Extremely fast switching
- Avalanche capability specified
- AEC-Q101 qualified

Description

Dual center tap Schottky rectifier suited for high frequency DC to DC converters.

Packaged in D²PAK, this device is especially intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications.

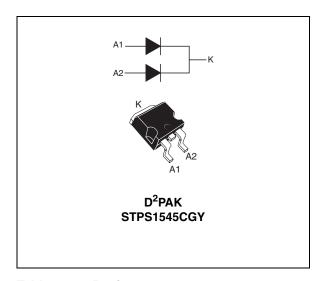


Table 1. Device summary

I _{F(AV)}	2 x 7.5 A
V _{RRM}	45 V
T _{j (max)}	175 °C
V _{F(max)}	0.57 V

Characteristics STPS1545C-Y

1 Characteristics

Table 2. Absolute Ratings (limiting values)

Symbol	Parameter			Value	Unit
V _{RRM}	Repetitive peak reverse voltage			45	V
I _{F(RMS)}	RMS forward voltage			20	Α
I _{F(AV)}	Average forward current $\delta = 0.5$	T _c = 157 °C Per diode		7.5	Α
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms Sinusoidal		150	Α
I _{RRM}	Peak repetitive reverse current	t _p = 2 μs square F = 1 kHz		1	Α
I _{RSM}	Non repetitive peak reverse current $t_p = 100 \mu s$ square			2	Α
P _{ARM}	Repetitive peak avalanche power $t_p = 1 \mu s T_j = 25 °C$			2700	W
T _{stg}	Storage temperature range			-65 to +175	°C
T _j	Maximum operating junction temperature (1)			-40 to +175	°C
dV/dt	Critical rate of rise of reverse voltage			10000	V/µs

^{1.} $\frac{dPtot}{dTj} < \frac{1}{Rth(j-a)}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal resistances

Symbol	Parameter	Value	Unit	
R _{th(j-c)}	Junction to case	Per diode Total	3.0 1.7	°C/W
R _{th(c)}	Coupling	0.35		

When the diodes 1 and 2 are used simultaneously : Δ Tj(diode 1) = P(diode1) x R_{th(j-c)}(Per diode) + P(diode 2) x R_{th(c)}

Table 4. Static electrical characteristics (per diode)

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
I _R ⁽¹⁾ Reverse leakage current	Payaraa laakaga aurrant	T _j = 25 °C	V -V	-	-	100	μΑ
	T _j = 125 °C	$V_R = V_{RRM}$	-	5	15	mA	
V _F ⁽¹⁾ Forward vo		T _j = 125 °C	I _F = 7.5A	-	0.5	0.57	
	Forward voltage drop	T _j = 25 °C	I _F = 15 A	-	-	0.84	٧
		T _j = 125 °C	I _F = 15 A	-	0.65	0.72	

^{1.} Pulse test: tp = 380 μ s, δ < 2%

To evaluate the conduction losses use the following equation:

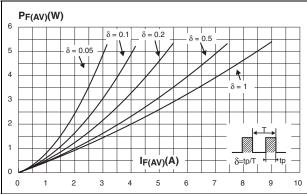
$$P = 0.42 \text{ x } I_{F(AV)} + 0.020 I_{F}^{2}_{(RMS)}$$

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STPS1545C-Y Characteristics

Figure 1. Average forward power dissipation Figure 2. versus average forward current (per diode)

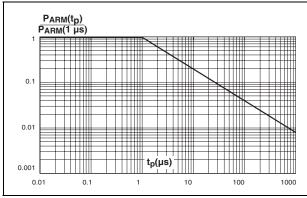
Average forward current versus ambient temperature $(\delta = 0.5, per diode)$



IF(AV)(A) 8 6 Rth(j-a)=40°C/W 5 4 3 2 T_{amb}(°C) δ=tp/T 0 50 75 100 0 25 125 175

Figure 3. Normalized avalanche power derating versus pulse duration

Figure 4. Normalized avalanche power derating versus junction temperature



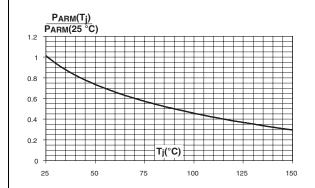
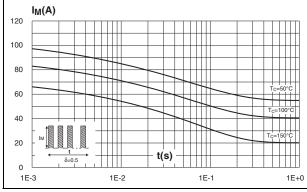
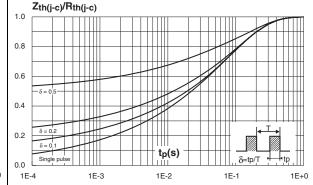


Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values, per diode)

Figure 6. Relative variation of thermal impedance junction to case versus pulse duration





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Figure 7. Reverse leakage current versus reverse voltage applied (typical values, per diode)

Figure 8. Junction capacitance versus reverse voltage applied (typical values, per diode)

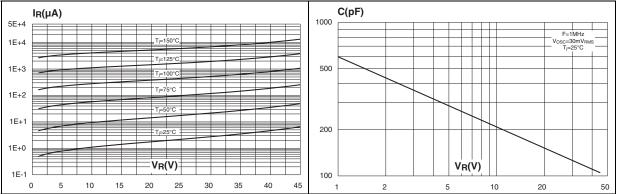
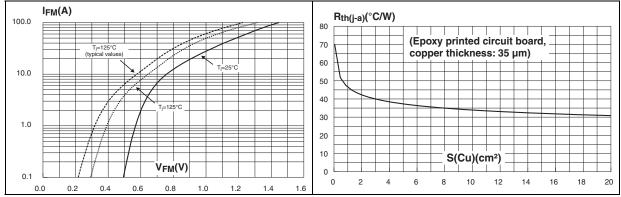


Figure 9. Forward voltage drop versus forward current (maximum values, per diode)

Figure 10. Thermal resistance junction to ambient versus copper surface under tab



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2 Package Information

- Epoxy meets UL94, V0
- Lead-free package

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

Figure 11. D²PAK dimensions

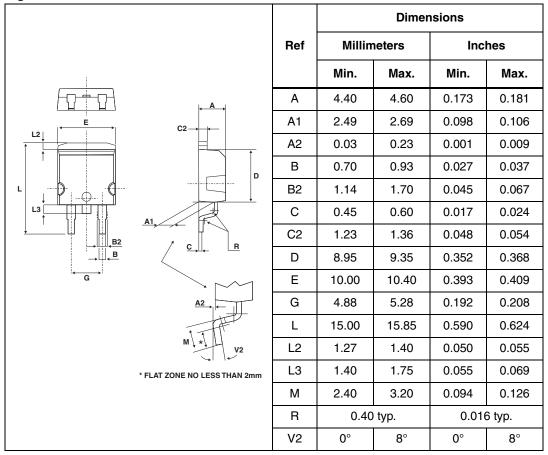
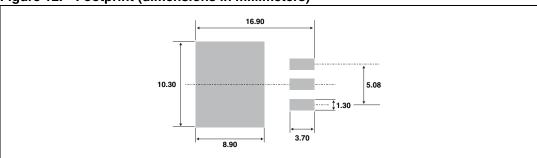


Figure 12. Footprint (dimensions in millimeters)



Ordering information STPS1545C-Y

3 Ordering information

Table 5. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS1545CGY-TR	STPS1545CGY	D ² PAK	1.48 g	1000	Tape and reel

4 Revision history

Table 6. Document revision history

Date	Revision	Changes
23-May-2011	1	Initial release.

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